

FIG. 1a  
(Prior art)

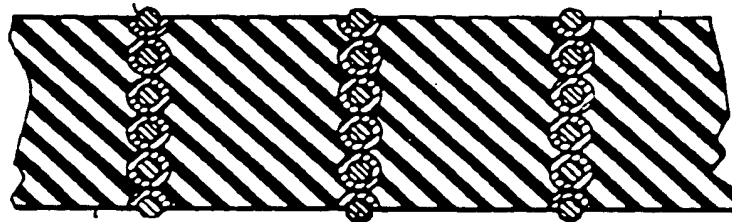


FIG. 1b  
(Plasma etched)

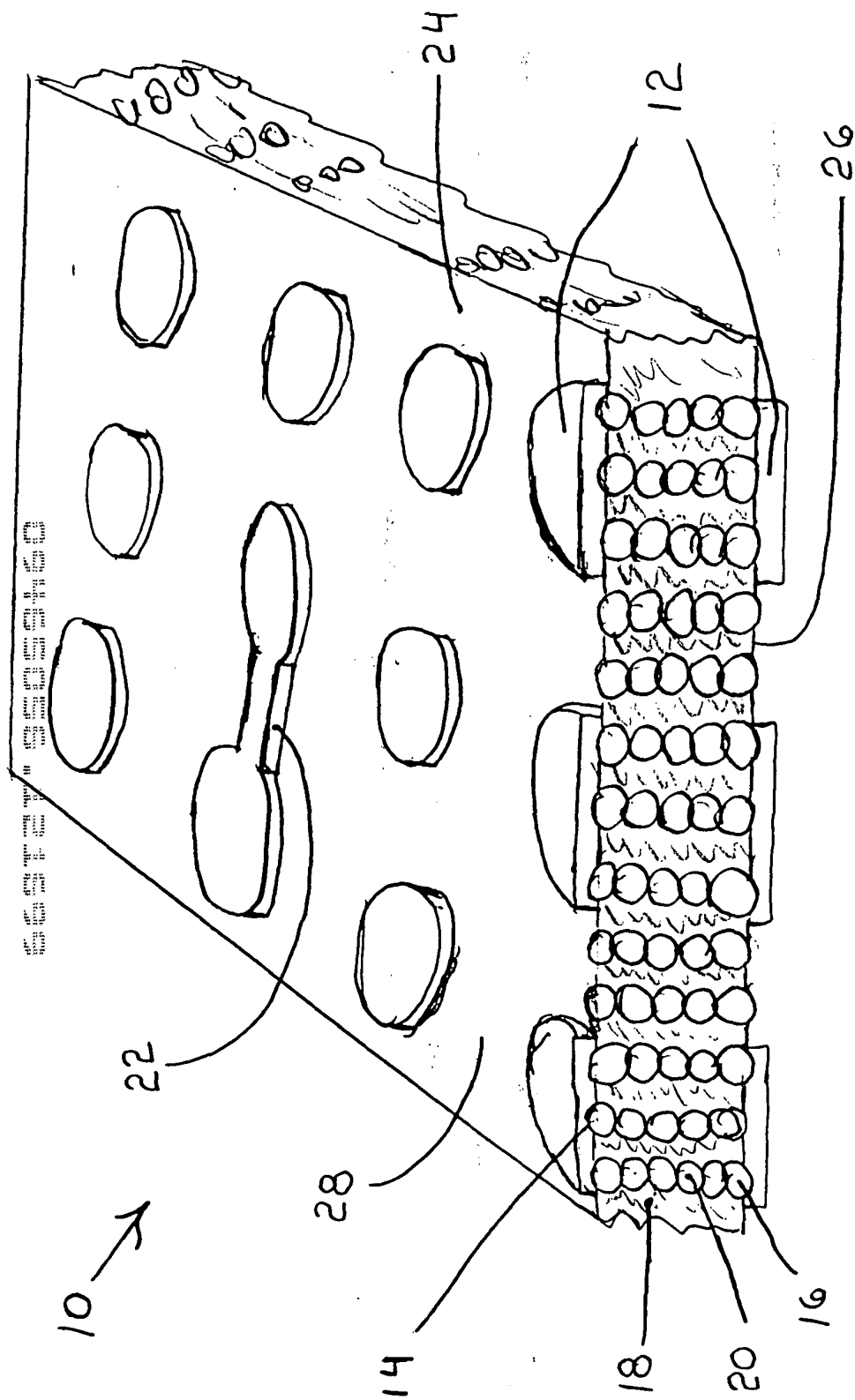


FIG. 2

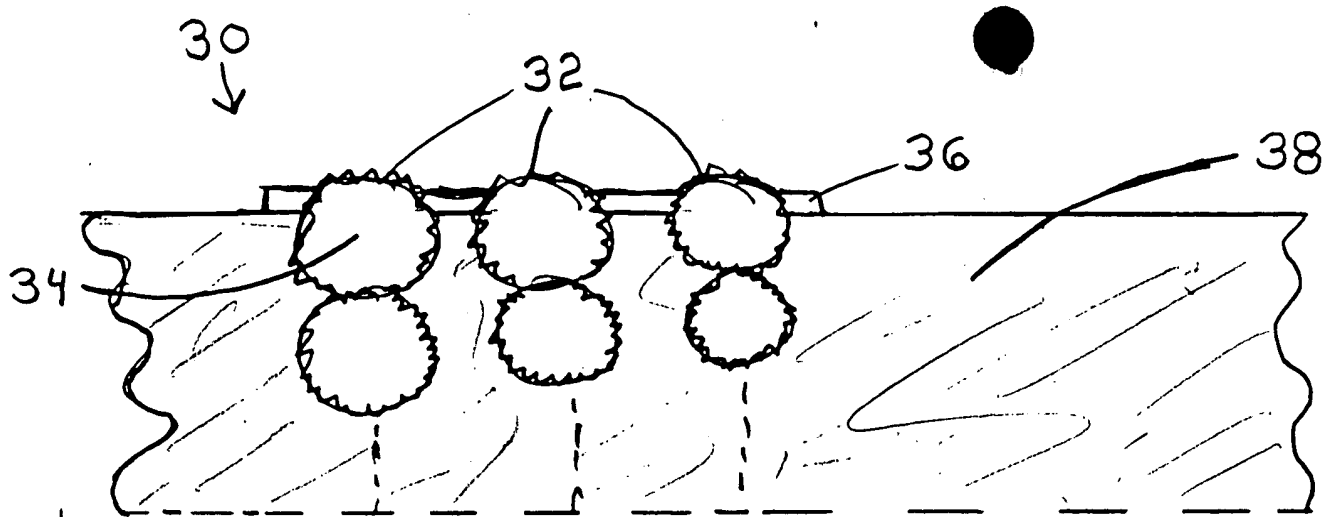


FIG. 3

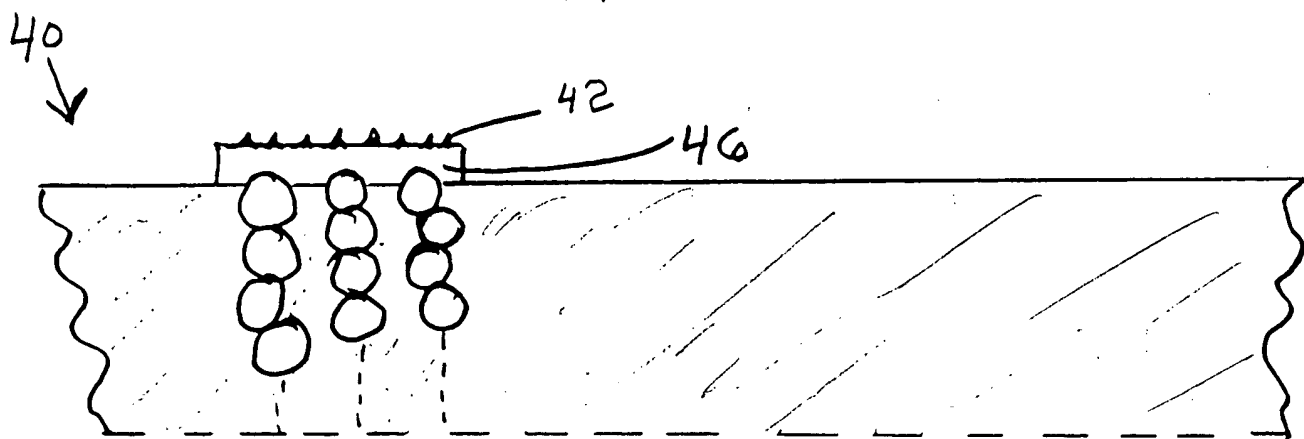


FIG. 4

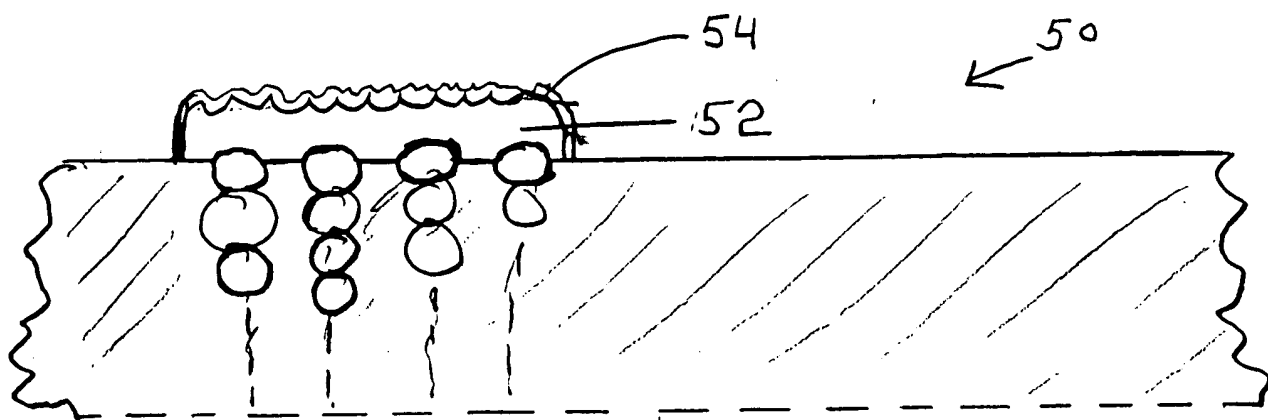
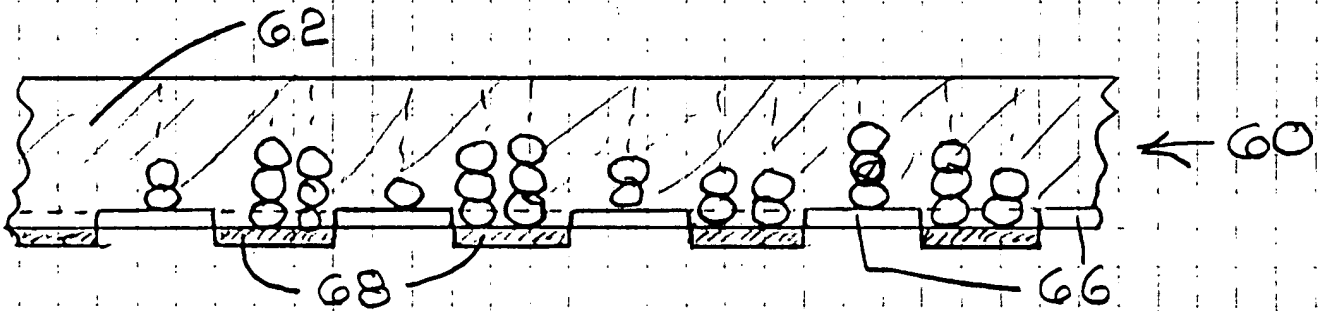
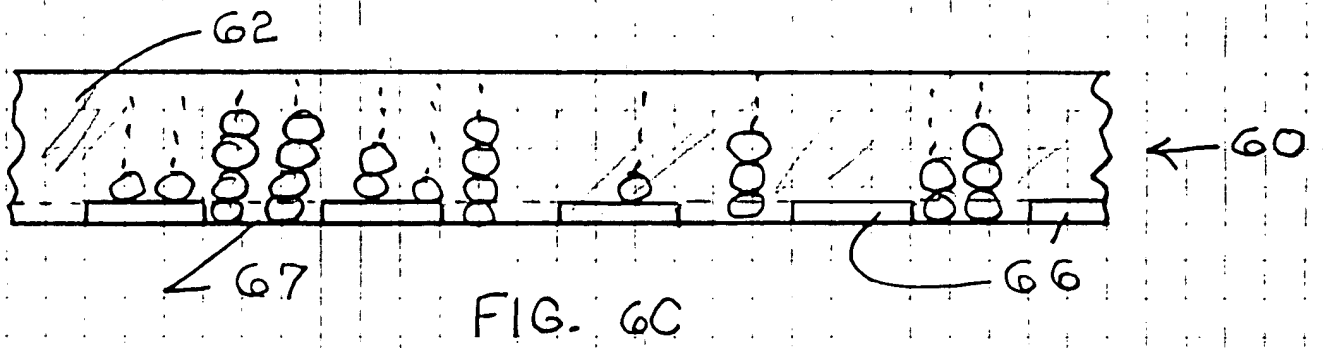
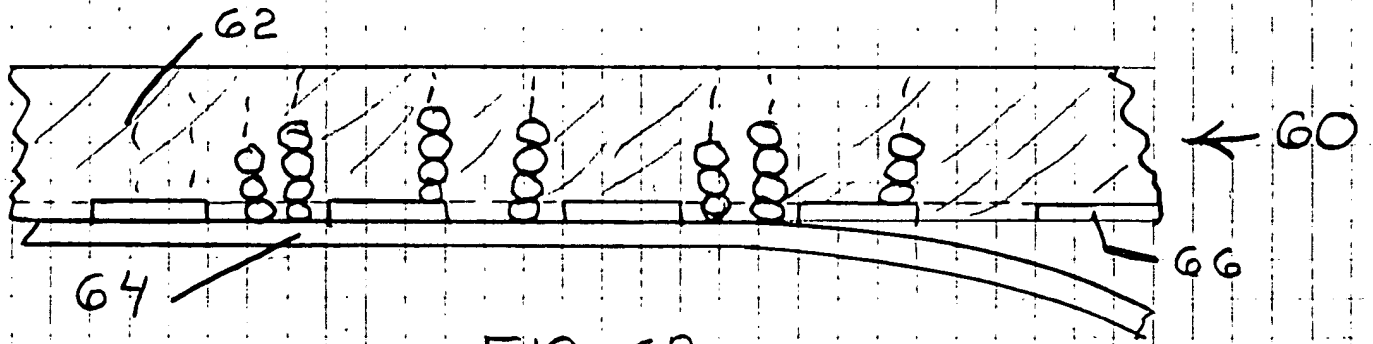
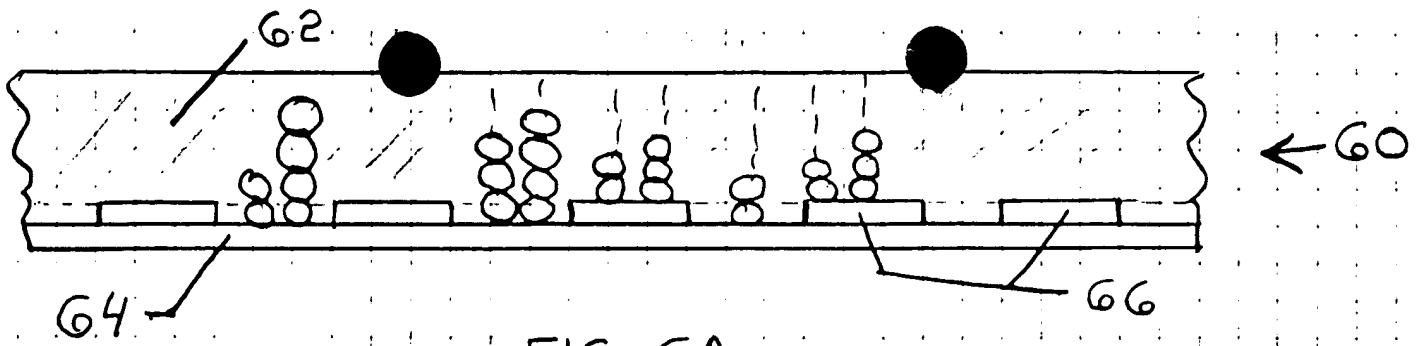


FIG. 5



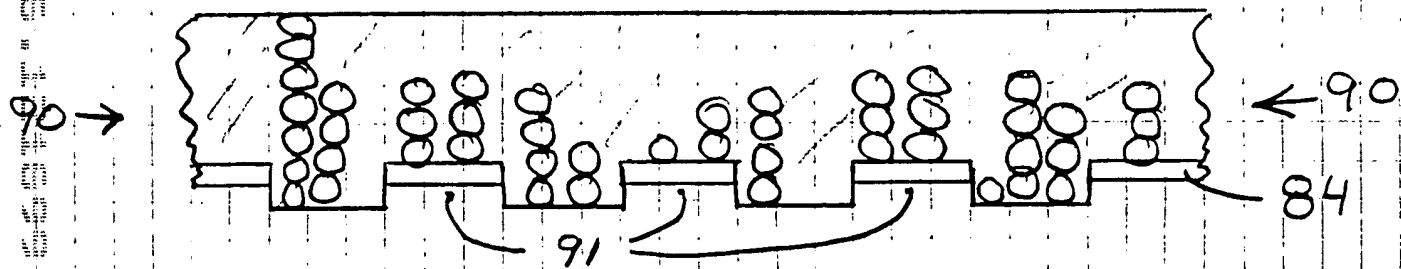
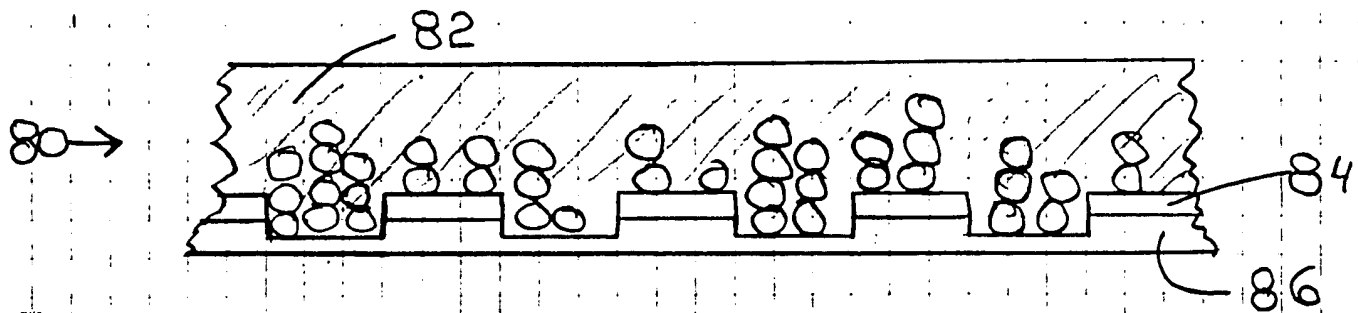
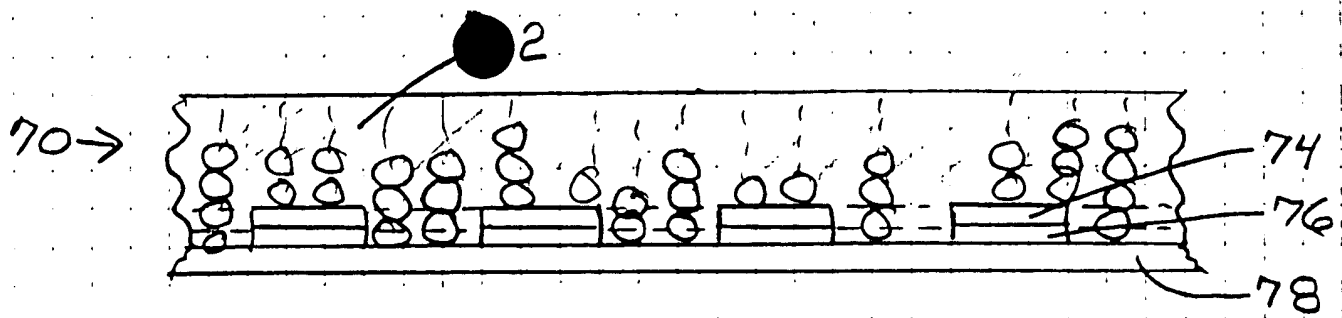


FIG. 10 is a cross-sectional view of a device in accordance with the present invention. The device includes a substrate 100, a layer 102, and a layer 104. A series of openings 80 are formed in the substrate 100, and a series of openings 82 are formed in the layer 102. A series of openings 84 are formed in the layer 104. The openings 80, 82, and 84 are aligned with each other.

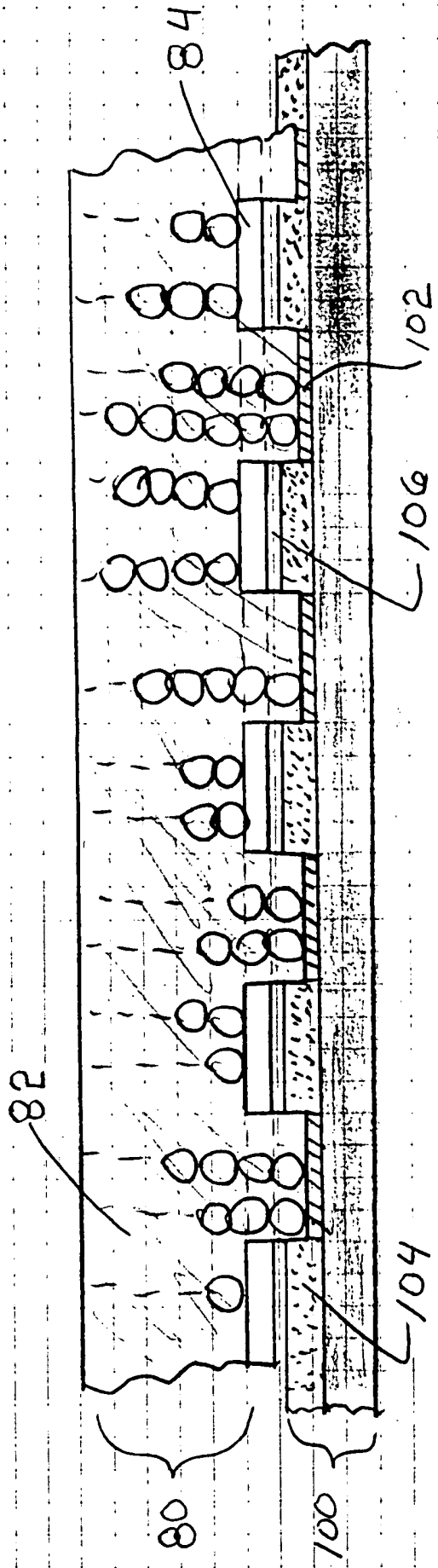


FIG. 10

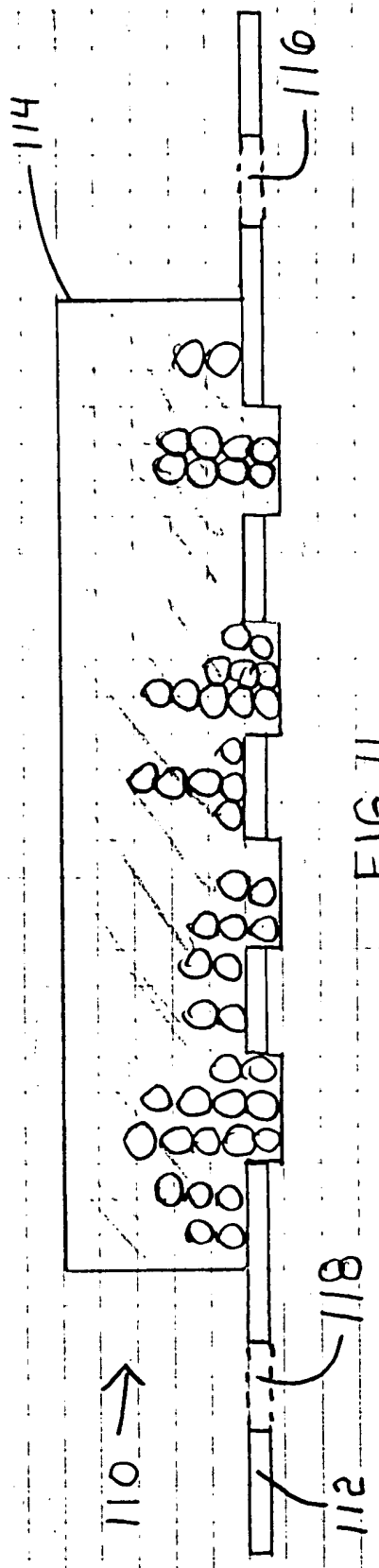
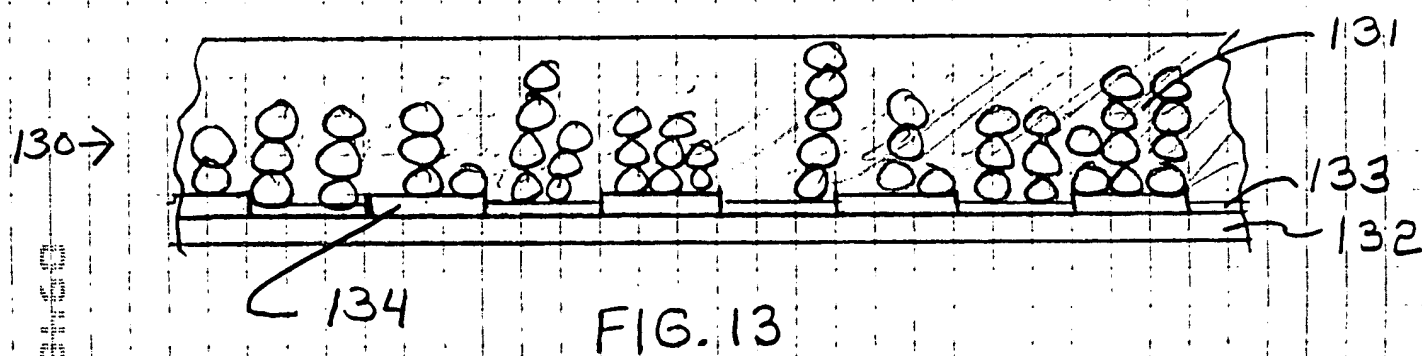
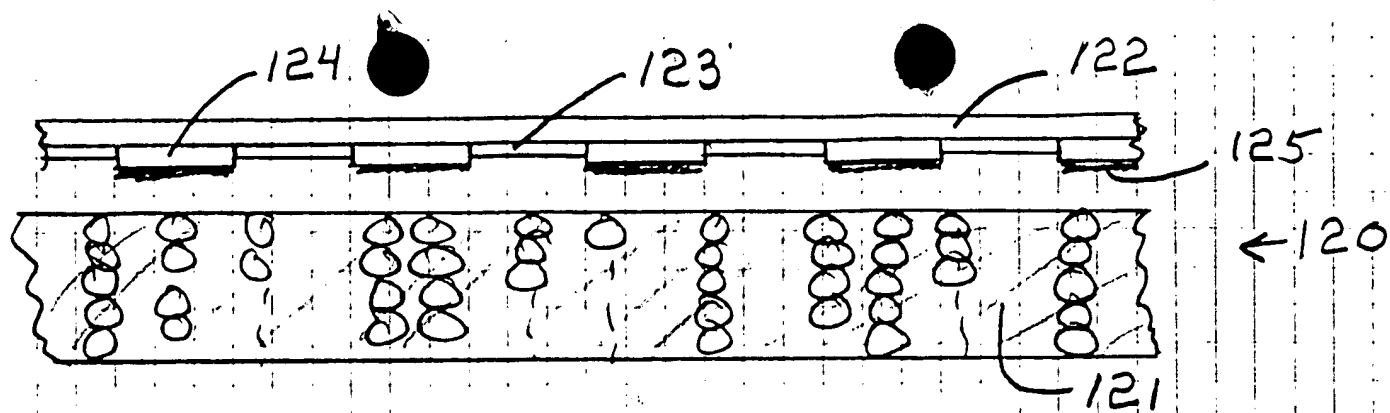


FIG. 11



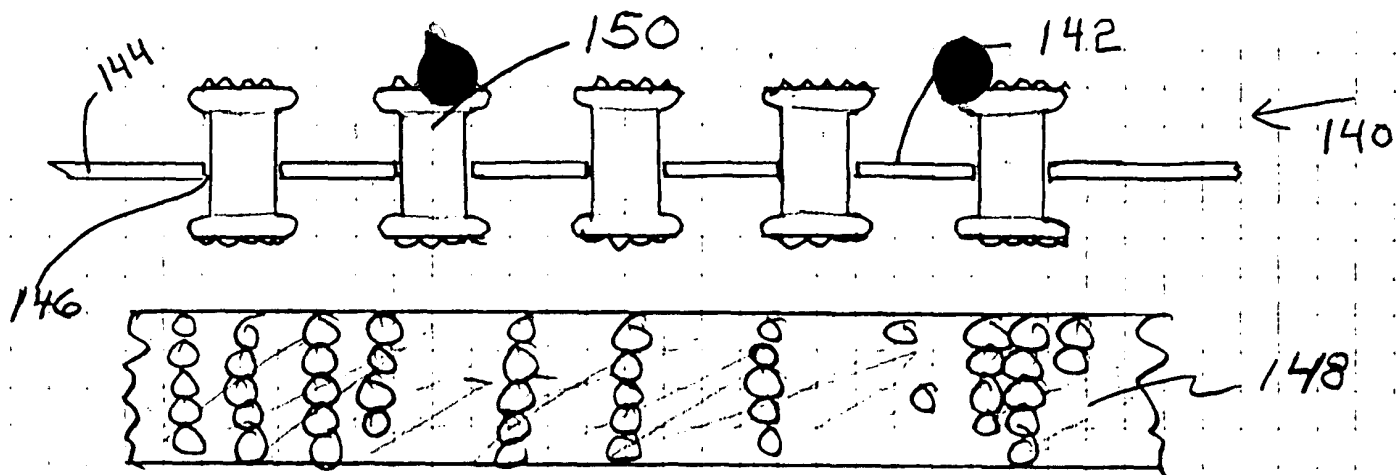


FIG. 14

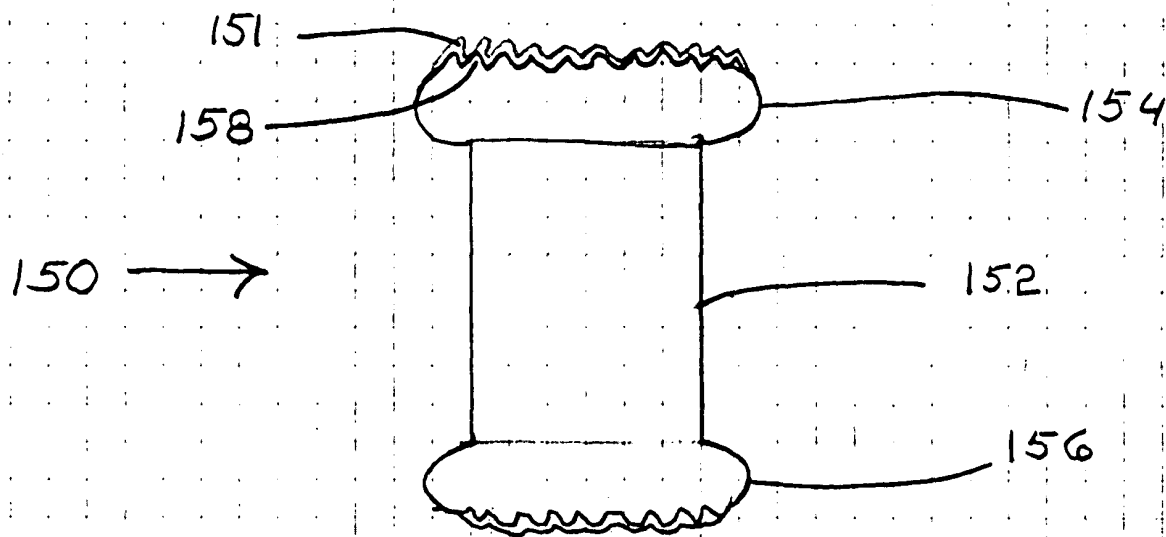


FIG. 15

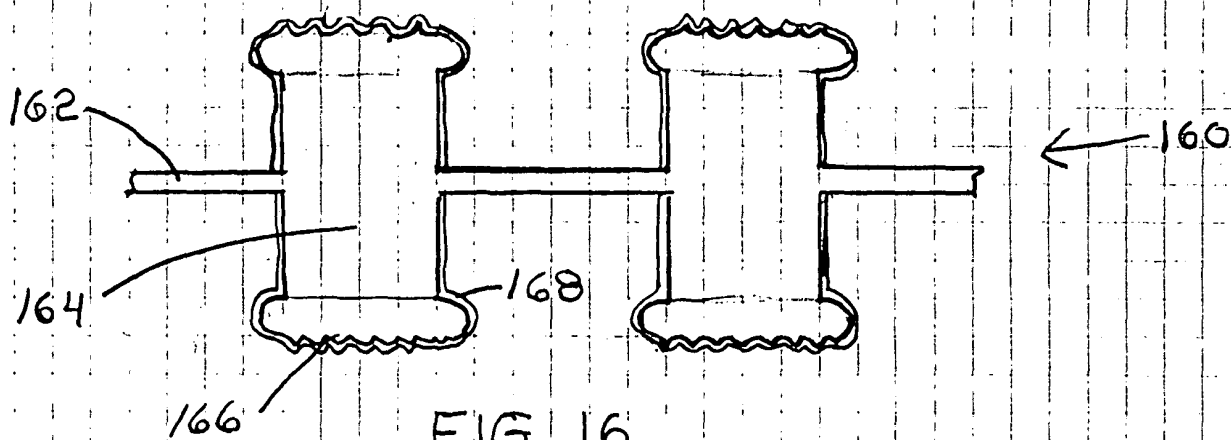


FIG. 16



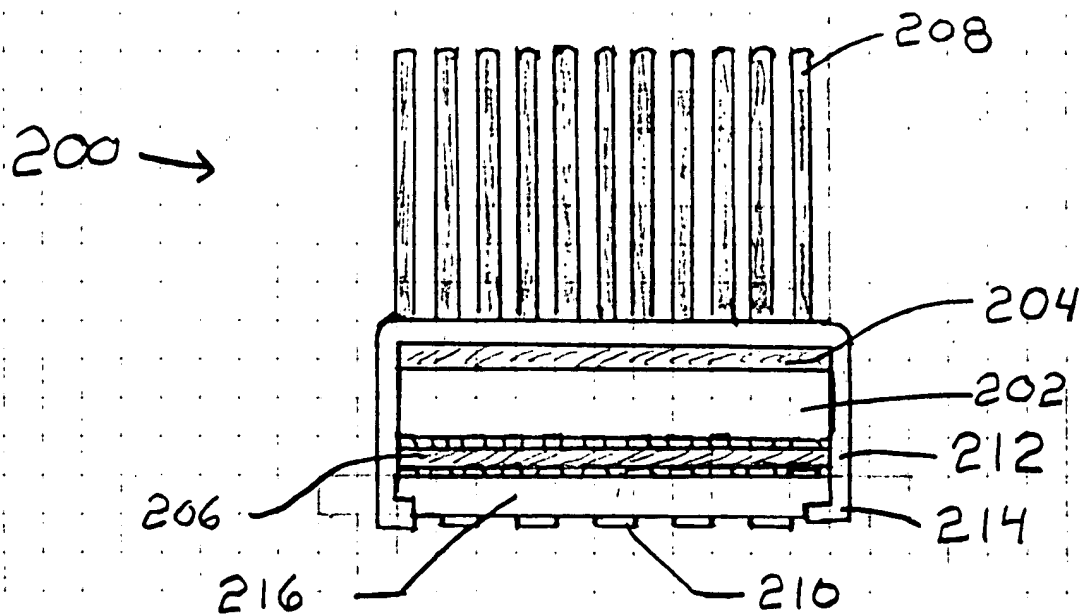


FIG. 17